

20th European Wet & 49th European CMP User Group Meeting

Wet- and CMP-Session: Thursday, November 27, 2025, 12:30 – 17:45

CMP-Session: Friday, November 28, 2024, 2025, 8:30 – 13:20

Abbaey Royaumont, Asnières sur Oise, France

Organized by European CMP&WET User Group and supported by Technic France

Agenda Thursday, November 27th

12:30 – 13:40 Welcome Coffee, Tea, Softdrinks and Light Lunch

13:40 Opening Remarks & Welcome
Knut Gottfried
Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany

Wet Session

Session Chair: Knut Gottfried, Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany

13:45 A Comparative Study of Single-Wafer Megasonic Cleaning Systems
Kazuaki Arai
Kaijo Shibuya Europe, Heidelberg, Germany

14:00 ACE by RENA: First SiC Wet Etching
Martin Pretscher¹, Norbert Bay¹, Athul Rathnakar², Xavier Gay¹, Wyatt Engler¹, Rahim Hamid¹, Franck Delahaye¹, Oliver Whear¹, Vishal A. Shah², and Holger Kuehnlein¹
¹RENA Technologies GmbH, Gütenbach, Germany, ²School of Engineering, University of Warwick, Coventry, UK

14:15 AP&S FlowSim – The way to tune your processes
Stefan Zürcher and Simon Gräfner
AP&S, Donaueschingen, Germany

14:30 Sponsor Pitch
Manuel Santana
White Knight/Innodys, Mennecy, France

14:35 From Reactive to Responsive: Mechanochemical Pathways for Stimuli-Activated Surface Cleaning
Connor J. Keating, Piper M. Smith, Cesar D. Alvarado, Andrew C. Murphy, Nicole A. Staszak, Austin J. Rockaitis, and Jason Keleher
Lewis University, Romeoville, IL, USA

15:00 Wet Processes for Advanced Packaging Technologies
Harold le Tulzo, Marine Audouin, Diane Bijou, Rogelio J. Gomez Pineiro, Loriana Celeste, Anaïs Passelande, Gaël Galantine, Audrey Valette, Jérôme Daviot
Technic France, La Plaine Saint Denis, France

15:25 Sponsor Pitch
Donald Dussault
ProSys, Campbell, CA, USA

15:30 **Coffee Break**

CMP Session 1: CMP Processes and Tutorial CMP

Session Chair: Gerfried Zwicker, zwickerconsult, Berlin, Germany

- 16:00 CMP development for Ultra-Scaled Back-End TiN Contacts for High Density Memory Applications
Floriane Baudin
CEA Leti, Grenoble, France
- 16:15 From Vibration to Variation – A Methodology for Correlating Machine Dynamics and Wafer Surface Topography in STI CMP via Scatterometry
Boris Brodmann², Etienne Babnik¹, and Ara Philipossian³
¹NanoFocus GmbH, Oberhausen, Germany, ²OptoSurf GmbH, Ettlingen, Germany, ³Araca Inc., Tucson, AZ, USA
- 16:45 Sponsor Pitch
Tom Sittig
PTW Europe GmbH, Dresden Germany
- 16:50 Tutorial: Advanced CMP Applications
Federico Barbieri
Entegris/CMC Materials, Barry / Vale of Glamorgan, UK
- 17:40 Trainee Mentoring Program
Catharina Rudolph
Fraunhofer IZM-ASSID, Dresden, Germany
- 17:45 End of Wet Users Meeting / time for networking and discussion
- 18:00 Champagne reception, sponsored by Technic France
- 19:00 Workshop Dinner at Abbey Royaumont

Agenda Friday, November 28th

8:30 – 9:00 Good Morning Coffee, Tea, Softdrinks

9:00 Opening Remarks
Martin Kulawski
Advaplan, Espoo, Finland

CMP Session 2: CMP Processes

Session Chair: Martin Kulawski, Advaplan, Espoo, Finland

- 9:05 Tuning Interfacial Reactions for Low-Stress and Self-Cleaning CMP Performance
Elizabeth M. McDonnell, Austin J. Rockaitis, Connor J. Keating, Andrew C. Murphy, and Jason Keleher
Lewis University, Romeoville, IL, USA
- 9:30 Dishing Dependency on Polishing Pressure and Time – STI CMP
Awwal Adesunkanmi and Andreas Krüger
Leibniz Institute for High Performance Microelectronics, Frankfurt/Oder, Germany

- 9:45 Impact of Sub-Optimal *In-Situ* Pad Conditioning Recipes on Process Vibrations in Copper CMP
Ara Philipossian, Yasa Sampurno, and Leonard Borucki
Araca Inc., Tucson, AZ, USA
- 10:10 CMP modelling for mask design and process improvement at imec
Karl Ceulemans, Kevin Vandersmissen, Catarina Regra Da Silva, and Juergen Boemmels
Imec, Leuven, Belgium
- 10:25 Exploring the Potential of Machine Learning in Developing CMP Slurry Composition
Akihiro Orita
Resonac, Hitachi, Japan
- 10:50 [Sponsor Pitch](#)
Fabien Durix
Ebara Precision Machinery Europe, Hanau, Germany
- 10:55 **Coffee Break**
- CMP Session 3: CMP Processes**
Session Chair: Catharina Rudolph, Fraunhofer IZM-ASSID, Dresden, Germany
- 11:30 Emblem™ Pads: Next-gen High Performance Pads and Costumers Success
Ricardo Duyos Mateo, Olivier Cesbron, and Michael Hauck
Qnity Electronics, Wilmington, Delaware, USA
- 11:55 From Filtration to Planarisation: D2W CMP Consumable Set Evaluation
Clément Castan and Victor Soty
CEA Leti, Grenoble, France
- 12:20 Evolution, Roadmap, and Future Opportunities of Automated Atomic Force Microscope
Ryan Yoo
Park Systems GmbH, Mannheim, Germany
- 12:45 [Sponsor Pitch](#)
Kamil Wlotzka
Schunk Ingenieurkeramik GmbH, Willich, Germany
- 12:50 Interferometry Technology in Semiconductor
Samuel Seignovert
Precitec France, Chateauneuf-le-rouge, France
- 13:05 Highlights from ICPT 2025
Gerfried Zwicker
zwickerconsult, Berlin, Germany
- 13:20 End of CMP User Group Meeting / Time for Networking and Discussion
Coffee, Tea, Softdrinks, Snacks and Light Lunch